Dual 4-Stage Binary Ripple Counter with ÷ 2 and ÷ 5 Sections

High-Performance Silicon-Gate CMOS

The MC54/74HC390 is identical in pinout to the LS390. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs.

This device consists of two independent 4–bit counters, each composed of a divide–by–two and a divide–by–five section. The divide–by–two and divide–by–five counters have separate clock inputs, and can be cascaded to implement various combinations of \div 2 and/or \div 5 up to a \div 100 counter.

Flip—flops internal to the counters are triggered by high—to—low transitions of the clock input. A separate, asynchronous reset is provided for each 4—bit counter. State changes of the Q outputs do not occur simultaneously because of internal ripple delays. Therefore, decoded output signals are subject to decoding spikes and should not be used as clocks or strobes except when gated with the Clock of the HC390.

• Output Drive Capability: 10 LSTTL Loads

· Outputs Directly Interface to CMOS, NMOS, and TTL

Operating Voltage Range: 2 to 6 V

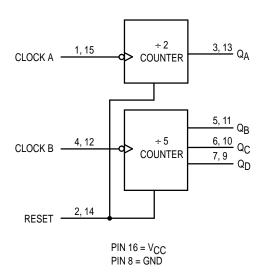
Low Input Current: 1 μA

• High Noise Immunity Characteristic of CMOS Devices

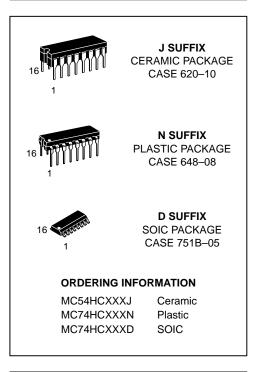
 In Compliance with the Requirements Defined by JEDEC Standard No 7A

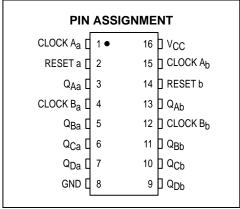
Chip Complexity: 244 FETs or 61 Equivalent Gates

LOGIC DIAGRAM



MC54/74HC390





FUNCTION TABLE Clock В Action Α Reset Χ Χ Н Reset 2 and ÷ 5 Χ L Increment ÷ 2 Χ ı Increment ÷ 5

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
VCC	DC Supply Voltage (Referenced to GND)	- 0.5 to + 7.0	V
V _{in}	DC Input Voltage (Referenced to GND)	- 1.5 to V _{CC} + 1.5	V
V _{out}	DC Output Voltage (Referenced to GND)	- 0.5 to V _{CC} + 0.5	V
I _{in}	DC Input Current, per Pin	± 20	mA
l _{out}	DC Output Current, per Pin	± 25	mA
ICC	DC Supply Current, V _{CC} and GND Pins	± 50	mA
PD	Power Dissipation in Still Air, Plastic or Ceramic DIP† SOIC Package†	750 500	mW
T _{stg}	Storage Temperature	- 65 to + 150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds (Plastic or SOIC DIP) (Ceramic DIP)	260 300	°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range GND \leq (V_{in} or V_{out}) \leq VCC. Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or VCC).

Unused outputs must be left open.

Functional operation should be restricted to the Recommended Operating Conditions.

†Derating — Plastic DIP: - 10 mW/°C from 65° to 125°C

Ceramic DIP: - 10 mW/°C from 100° to 125°C

SOIC Package: - 7 mW/°C from 65° to 125°C

For high frequency or heavy load considerations, see Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter			Max	Unit
VCC	DC Supply Voltage (Referenced to GND)			6.0	V
V _{in} , V _{out}	DC Input Voltage, Output Voltage (Referenced to GND)		0	VCC	V
TA	Operating Temperature, All Package Types		- 55	+ 125	°C
t _r , t _f	Input Rise and Fall Time (Figure 1)	V _{CC} = 2.0 V V _{CC} = 4.5 V V _{CC} = 6.0 V	0 0 0	1000 500 400	ns

DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

				Guaranteed Limit			
Symbol	Parameter	Test Conditions	v _{CC}	– 55 to 25°C	≤ 85°C	≤ 125°C	Unit
V _{IH}	Minimum High-Level Input Voltage	$V_{out} = 0.1 \text{ V or } V_{CC} - 0.1 \text{ V}$ $ I_{out} \le 20 \mu\text{A}$	2.0 4.5 6.0	1.5 3.15 4.2	1.5 3.15 4.2	1.5 3.15 4.2	V
V _{IL}	Maximum Low–Level Input Voltage	$V_{out} = 0.1 \text{ V or } V_{CC} - 0.1 \text{ V}$ $ I_{out} \le 20 \mu\text{A}$	2.0 4.5 6.0	0.3 0.9 1.2	0.3 0.9 1.2	0.3 0.9 1.2	٧
VOH	Minimum High–Level Output Voltage	$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out} \le 20 \mu\text{A}$	2.0 4.5 6.0	1.9 4.4 5.9	1.9 4.4 5.9	1.9 4.4 5.9	>
		$V_{\text{in}} = V_{\text{IH}} \text{ or } V_{\text{IL}} I_{\text{out}} \le 4.0 \text{ mA}$ $ I_{\text{out}} \le 5.2 \text{ mA}$	4.5 6.0	3.98 5.48	3.84 5.34	3.70 5.20	
VOL	Maximum Low–Level Output Voltage	$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out} \le 20 \mu\text{A}$	2.0 4.5 6.0	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	٧
		$V_{\text{in}} = V_{\text{IH}} \text{ or } V_{\text{IL}} I_{\text{out}} \le 4.0 \text{ mA}$ $ I_{\text{out}} \le 5.2 \text{ mA}$	4.5 6.0	0.26 0.26	0.33 0.33	0.40 0.40	
l _{in}	Maximum Input Leakage Current	$V_{in} = V_{CC}$ or GND	6.0	± 0.1	± 1.0	± 1.0	μΑ
lcc	Maximum Quiescent Supply Current (per Package)	$V_{in} = V_{CC}$ or GND $I_{out} = 0 \mu A$	6.0	8	80	160	μΑ

NOTE: Information on typical parametric values can be found in Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).

^{*} Maximum Ratings are those values beyond which damage to the device may occur.

AC ELECTRICAL CHARACTERISTICS ($C_L = 50 \text{ pF}$, Input $t_f = t_f = 6 \text{ ns}$)

			Guaranteed Limit			
Symbol	Parameter	V _{CC}	– 55 to 25°C	≤ 85°C	≤ 125°C	Unit
^f max	Maximum Clock Frequency (50% Duty Cycle) (Figures 1 and 3)	2.0 4.5 6.0	5.4 27 32	4.4 22 26	3.6 18 21	MHz
tPLH, tPHL	Maximum Propagation Delay, Clock A to QA (Figures 1 and 3)	2.0 4.5 6.0	120 24 20	150 30 26	180 36 31	ns
tPLH, tPHL	Maximum Propagation Delay, Clock A to QC (QA connected to Clock B) (Figures 1 and 3)	2.0 4.5 6.0	290 58 49	365 73 62	435 87 74	ns
tPLH, tPHL	Maximum Propagation Delay, Clock B to QB (Figures 1 and 3)	2.0 4.5 6.0	130 26 22	165 33 28	195 39 33	ns
t _{PLH} , t _{PHL}	Maximum Propagation Delay, Clock B to QC (Figures 1 and 3)	2.0 4.5 6.0	185 37 31	230 46 39	280 56 48	ns
tPLH, tPHL	Maximum Propagation Delay, Clock B to QD (Figures 1 and 3)	2.0 4.5 6.0	130 26 22	165 33 28	195 39 33	ns
[†] PHL	Maximum Propagation Delay, Reset to any Q (Figures 2 and 3)	2.0 4.5 6.0	165 33 28	205 41 35	250 50 43	ns
t _{TLH} , t _{THL}	Maximum Output Transition Time, Any Output (Figures 1 and 3)	2.0 4.5 6.0	75 15 13	95 19 16	110 22 19	ns
C _{in}	Maximum Input Capacitance	_	10	10	10	pF

NOTES:

- 1. For propagation delays with loads other than 50 pF, see Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).
- 2. Information on typical parametric values can be found in Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).

		Typical @ 25°C, V _{CC} = 5.0 V	
C_{PD}	Power Dissipation Capacitance (Per Counter)*	35	pF

^{*} Used to determine the no–load dynamic power consumption: $P_D = C_{PD} \ V_{CC}^2 f + I_{CC} \ V_{CC}$. For load considerations, see Chapter 2 of the Motorola High–Speed CMOS Data Book (DL129/D).

TIMING REQUIREMENTS (Input $t_f = t_f = 6 \text{ ns}$)

			Guaranteed Limit			
Symbol	Parameter	v _{CC}	– 55 to 25°C	≤ 85°C	≤ 125°C	Unit
t _{rec}	Minimum Recovery Time, Reset Inactive to Clock A or Clock B (Figure 2)	2.0 4.5 6.0	50 10 9	65 13 11	75 15 13	ns
t _W	Minimum Pulse Width, Clock A, Clock B (Figure 1)	2.0 4.5 6.0	80 16 14	100 20 17	120 24 20	ns
t _W	Minimum Pulse Width, Reset (Figure 2)	2.0 4.5 6.0	125 25 21	155 31 26	190 38 32	ns
t _f , t _f	Maximum Input Rise and Fall Times (Figure 1)	2.0 4.5 6.0	1000 500 400	1000 500 400	1000 500 400	ns

NOTE: Information on typical parametric values can be found in Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).

PIN DESCRIPTIONS

INPUTS

Clock A (Pins 1, 15) and Clock B (Pins 4, 15)

Clock A is the clock input to the \div 2 counter; Clock B is the clock input to the \div 5 counter. The internal flip–flops are toggled by high–to–low transitions of the clock input.

CONTROL INPUTS

Reset (Pins 2, 14)

Asynchronous reset. A high at the Reset input prevents counting, resets the internal flip–flops, and forces Q_A through Q_D low.

OUTPUTS

QA (Pins 3, 13)

Output of the ÷ 2 counter.

QB, QC, QD (Pins 5, 6, 7, 9, 10, 11)

Outputs of the \div 5 counter. Q_D is the most significant bit. Q_A is the least significant bit when the counter is connected for BCD output as in Figure 4. Q_B is the least significant bit when the counter is operating in the bi–quinary mode as in Figure 5.

VCC

GND

VCC

GND

SWITCHING WAVEFORMS

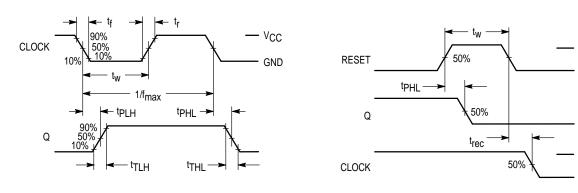
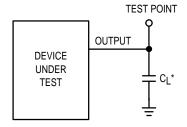


Figure 1.

Figure 2.

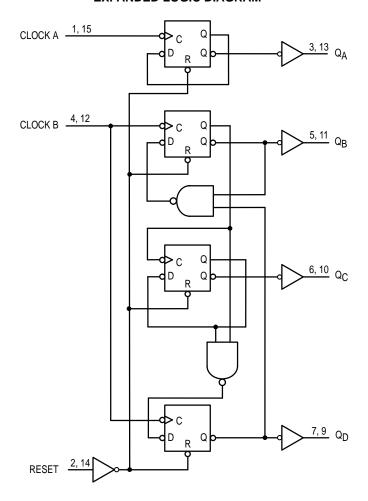
TEST CIRCUIT



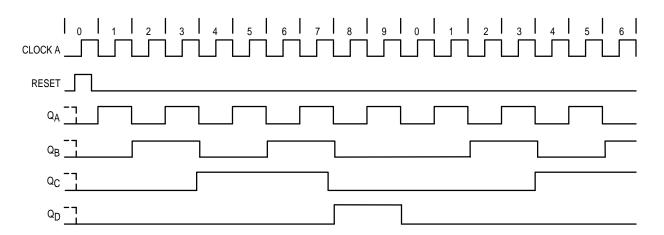
* Includes all probe and jig capacitance

Figure 3.

EXPANDED LOGIC DIAGRAM



TIMING DIAGRAM (QA Connected to Clock B)



APPLICATIONS INFORMATION

Each half of the MC54/74HC390 has independent \div 2 and \div 5 sections (except for the Reset function). The \div 2 and \div 5 counters can be connected to give BCD or bi–quinary (2–5) count sequences. If Output Q_A is connected to the Clock B input (Figure 4), a decade divider with BCD output is obtained. The function table for the BCD count sequence is given in Table 1.

To obtain a bi–quinary count sequence, the input signals connected to the Clock B input, and output QD is connected to the Clock A input (Figure 5). QA provides a 50% duty cycle output. The bi–quinary count sequence function table is given in Table 2.

Table 1. BCD Count Sequence*

	Output					
Count	QD	σc	QB	Q_{A}		
0	L	L	L	L		
1	L	L	L	Н		
2	L	L	Н	L		
3	L	L	Н	Н		
4	L	Н	L	L		
5	L	Н	L	Н		
6	L	Н	Н	L		
7	L	Н	Н	Н		
8	Н	L	L	L		
9	Н	L	L	Н		

^{*} QA connected to Clock B input.

Table 2. Bi-Quinary Count Sequence**

	Output					
Count	QA	QD	ФС	QB		
0	L	L	L	L		
1	L	L	L	Н		
2	L	L	Н	L		
3	L	L	Н	Н		
4	L	Н	L	L		
8	Н	L	L	L		
9	Н	L	L	Н		
10	Н	L	Н	L		
11	Н	L	Н	Н		
12	Н	Н	L	L		

^{**} QD connected to Clock A input.

CONNECTION DIAGRAMS

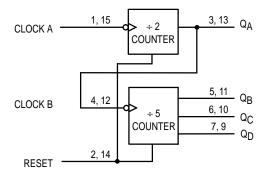


Figure 4. BCD Count

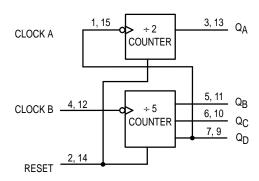
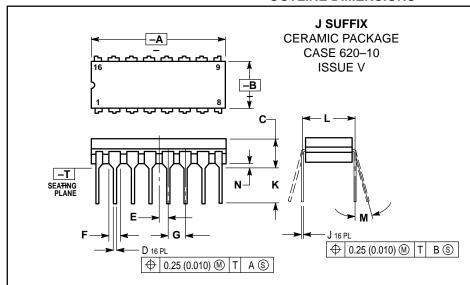


Figure 5. Bi-Quinary Count

OUTLINE DIMENSIONS



В

D 16 PL

⊕ 0.25 (0.010) M T A M

-A

G

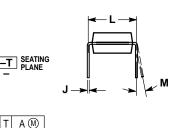
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- NOTES:
 1. DIMENSIONING AND TOLERANCING PER
- ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: INCH.
 DIMENSION L TO CENTER OF LEAD WHEN
 FORMED PARALLEL.
- 4. DIM F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.750	0.785	19.05	19.93
В	0.240	0.295	6.10	7.49
С	_	0.200	_	5.08
D	0.015	0.020	0.39	0.50
Е	0.050 BSC		1.27	BSC
F	0.055	0.065	1.40	1.65
G	0.100 BSC		2.54	BSC
J	0.008	0.015	0.21	0.38
K	0.125	0.170	3.18	4.31
L	0.300) BSC	7.62	BSC
M	0°	15°	0°	15°
N	0.020	0.040	0.51	1.01

N SUFFIX

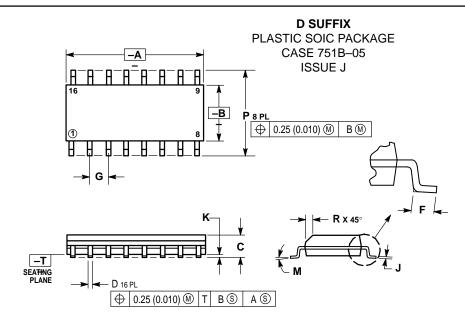
PLASTIC PACKAGE CASE 648-08 **ISSUE R**



NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL. DIMENSION B DOES NOT INCLUDE MOLD FLASH. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.740	0.770	18.80	19.55
В	0.250	0.270	6.35	6.85
С	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.070	1.02	1.77
G	0.	100 BSC	2	.54 BSC
Н	0.	050 BSC	1	.27 BSC
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
S	0.020	0.040	0.51	1.01



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- T 14-30M, 1962.
 CONTROLLING DIMENSION: MILLIMETER.
 DIMENSIONS A AND B DO NOT INCLUDE
 MOLD PROTRUSION.
 MAXIMUM MOLD PROTRUSION 0.15 (0.006)

- 4. MAXIMUM MOLLD PROTRUSION 0.15 (0.006)
 PER SIDE.
 5. DIMENSION D DOES NOT INCLUDE DAMBAR
 PROTRUSION. ALLOWABLE DAMBAR
 PROTRUSION SHALL BE 0.127 (0.005) TOTAL
 IN EXCESS OF THE D DIMENSION AT

 MAXIMUM STEPLING DEBITION. MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	9.80	10.00	0.386	0.393
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.2	7 BSC	0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
М	0°	7°	0°	7°
Р	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

MC54/74HC390

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